



# 2PA1774xMB series

40 V, 100 mA PNP general-purpose transistors

Rev. 1 — 23 March 2012

Product data sheet

## 1. Product profile

### 1.1 General description

PNP general-purpose transistors in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number	Package			NPN complement
	Nexperia	JEITA	JEDEC	
2PA1774QMB	SOT883B	-	-	2PC4617QMB
2PA1774RMB	SOT883B	-	-	2PC4617RMB
2PA1774SMB	SOT883B	-	-	-

### 1.2 Features and benefits

- Leadless ultra small SMD plastic package
- Low package height of 0.37 mm
- Power dissipation comparable to SOT23
- AEC-Q101 qualified

### 1.3 Applications

- General-purpose switching and amplification
- Mobile applications

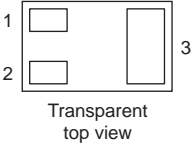
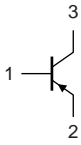
### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	-40	V
$I_C$	collector current		-	-	-100	mA
$h_{FE}$	DC current gain	$V_{CE} = -6\text{ V}; I_C = -1\text{ mA}$				
	2PA1774QMB		120	-	270	
	2PA1774RMB		180	-	390	
	2PA1774SMB		270	-	560	

## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base		
2	emitter		
3	collector		

*sym013*

## 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
2PA1774xMB series	DFN1006B-3	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.37 mm	SOT883B

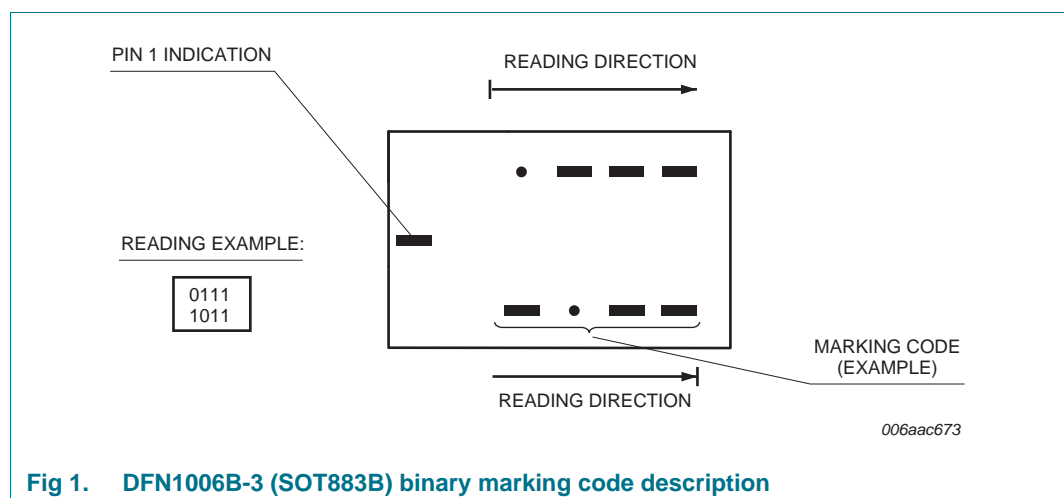
## 4. Marking

Table 5. Marking codes

Type number	Marking code <sup>[1]</sup>
2PA1774QMB	0100 0000
2PA1774RMB	0000 1101
2PA1774SMB	0000 1110

[1] For DFN1006B-3 (SOT883B) binary marking code description see [Figure 1](#).

### 4.1 Binary marking code description



## 5. Limiting values

**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{CBO}$	collector-base voltage	open emitter	-	-50	V	
$V_{CEO}$	collector-emitter voltage	open base	-	-40	V	
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V	
$I_C$	collector current		-	-100	mA	
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-200	mA	
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	-100	mA	
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1][2]	-	250	mW
			[3][2]	-	590	mW
$T_j$	junction temperature		-	150	°C	
$T_{amb}$	ambient temperature		-55	+150	°C	
$T_{stg}$	storage temperature		-65	+150	°C	

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, mounting pad for collector 1 cm<sup>2</sup>.

## 6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	500	K/W
			[3][2]	-	212	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, mounting pad for collector 1 cm<sup>2</sup>.

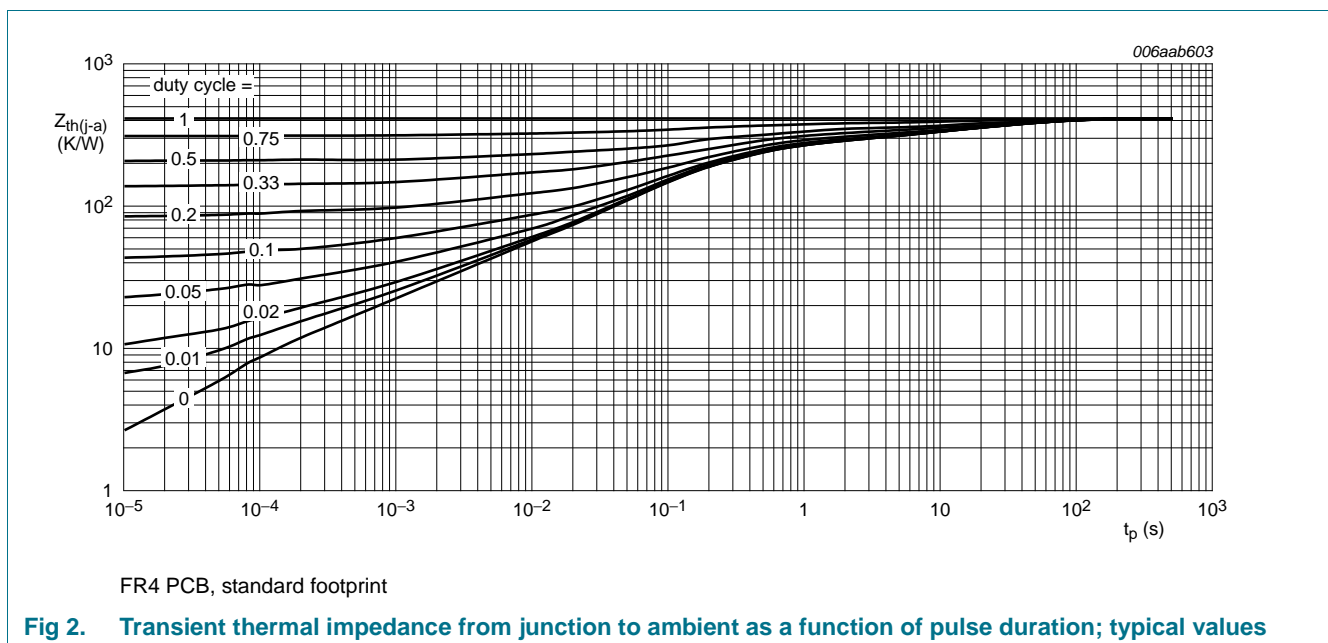


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

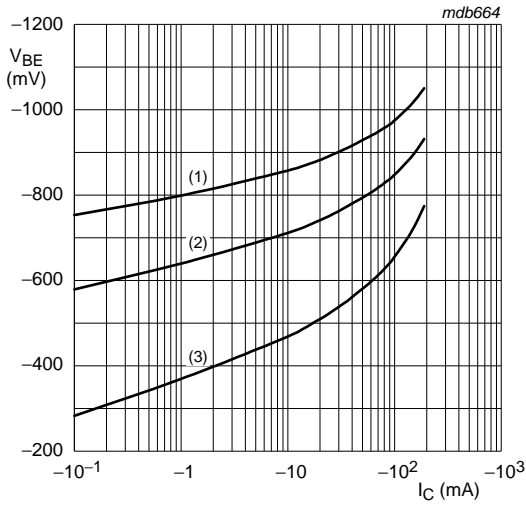
## 7. Characteristics

**Table 8. Characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

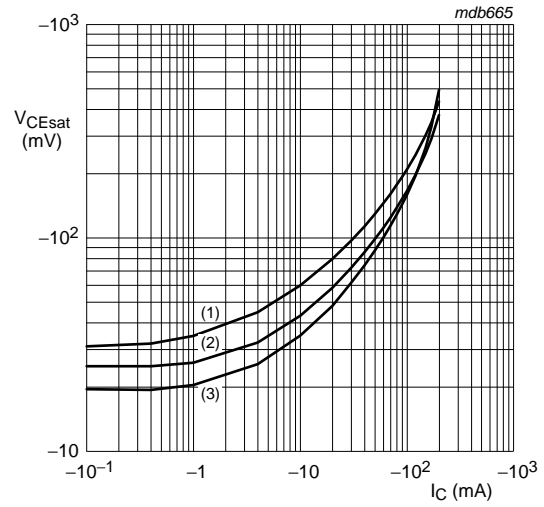
Symbol	Parameter	Conditions	Min	Typ	Max	Unit				
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0\text{ A}$	-	-	-100	nA				
		$V_{CB} = -30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$	-	-	-5	$\mu\text{A}$				
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -4\text{ V}; I_C = 0\text{ A}$	-	-	-100	nA				
$h_{FE}$	DC current gain	$V_{CE} = -6\text{ V}; I_C = -1\text{ mA}$								
							2PA1774QMB	120	-	270
							2PA1774RMB	180	-	390
							2PA1774SMB	270	-	560
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -50\text{ mA}; I_B = -5\text{ mA}$	[1]	-	-200	mV				
$f_T$	transition frequency	$V_{CE} = -12\text{ V}; I_C = -2\text{ mA}; f = 100\text{ MHz}$	100	-	-	MHz				
$C_c$	collector capacitance	$V_{CB} = -12\text{ V}; I_E = I_C = 0\text{ A}; f = 1\text{ MHz}$	-	-	2.2	pF				

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .



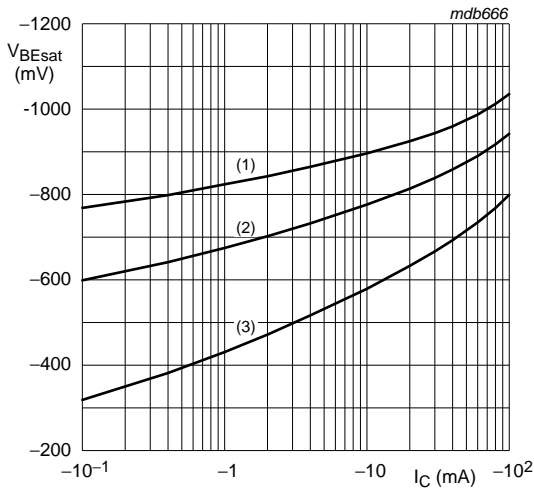
$V_{CE} = -6\text{ V}$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 150\text{ °C}$

**Fig. 3. Base-emitter voltage as a function of collector current; typical values**



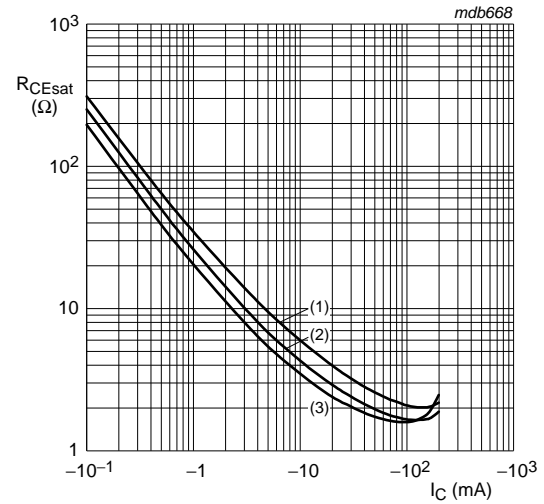
$I_C/I_B = 10$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig. 4. Collector-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 10$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 150\text{ °C}$

**Fig. 5. Base-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 10$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

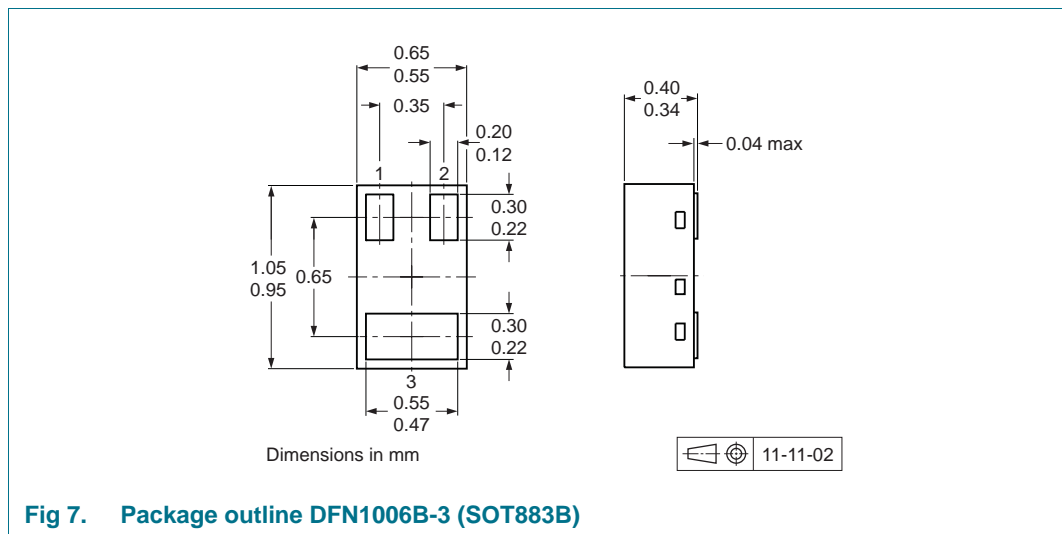
**Fig. 6. Collector-emitter equivalent on-resistance as a function of collector current; typical values**

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



## 10. Packing information

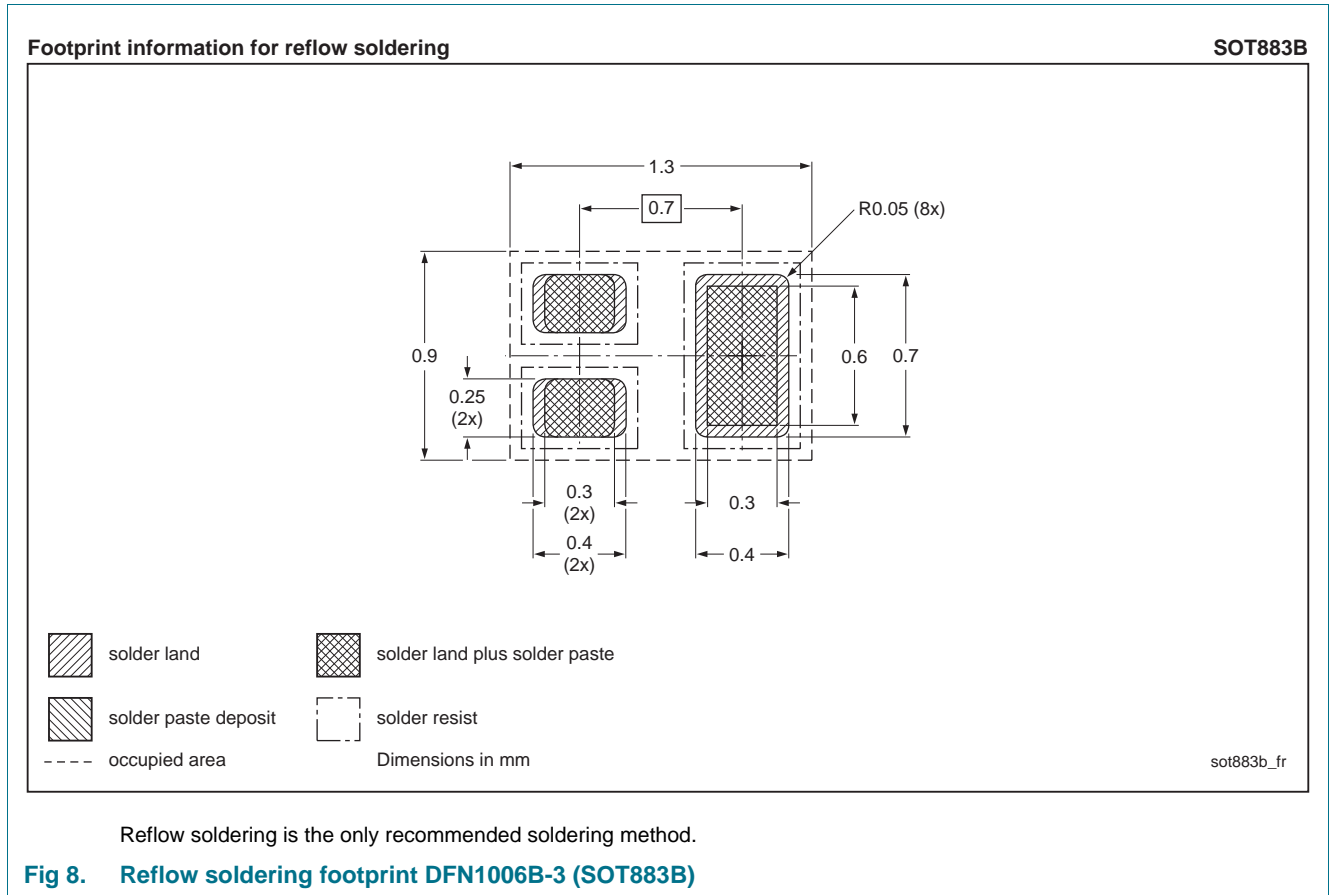
**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity
			<b>10000</b>
2PA1774xMB series	DFN1006B-3 (SOT883B)	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering





## 12. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PA1774XMB_SER v.1	20120323	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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